

What is claimed is:

1. A light emitting device comprising:

a base member having a plurality of electric conductive members with good heat conductivity and insulating members
5 securing and isolating each conductive member;

a light emitting diode mounted on one of the conductive members;

an electrically connecting means to connect the light emitting diode and the conductive members for applying
10 current to the light emitting element;

a sealing member covering the light emitting diode and the electrically connecting means for protection;

a projection outwardly stretched for heat release from the other side of the conductive member thereon the light
15 emitting diode mounted.

2. The device according to claim 1 characterized by the conductive member having a contact with an external cooling member for heat release.

3. The device according to claim 1 wherein the
20 electrically connecting means comprise a circuit substrate with a circuit pattern secured to the base member and at least a wire so as to apply the current to the light emitting diode; and

the circuit substrate having an opening so as to set
25 the light emitting diode on the conductive member directly.

4. The device according to claim 1 wherein the plurality of conductive members are made of metal core material.

5. The device according to claim 2 further comprising an external print substrate having a through-hole so as to insert the projection of the conductive member and contact the projection with the cooling member secured to
5 the other side of the print substrate.

6. The device according to claim 1 wherein the cooling member has a plurality of cooling fins.

7. A method for manufacturing a light emitting device comprising the steps of:

10 combining of conductive members with insulating members to form a base member assembly for a plurality of light emitting devices;

forming a circuit substrate assembly having a plurality of openings and circuit patterns for a plurality of light
15 emitting devices;

securing the circuit substrate assembly to the base member assembly;

mounting each light emitting diode on the conductive member exposed in each opening of the circuit substrate
20 assembly;

connecting each light emitting diode with each circuit pattern by at least a wire;

sealing the light emitting diodes and the wires on the circuit substrate assembly with a sealing member; and

25 separating each independent light emitting device by dicing.